

**AMENDMENTS**

**In the Claims:**

1. (Currently Amended) A curable composition that comprises a continuous phase and a dispersoid at ambient temperatures, wherein

the continuous phase is a liquid at ambient temperatures and comprises (a) a compound having two or more epoxy groups in a molecule,

the dispersoid ~~comprises~~ consists of (b) a compound present as solid particles in a continuous phase at ambient temperatures and having two or more primary amino groups in a molecule, and

the compound having two or more amino groups in a molecule is an aromatic amine compound having a benzoxazole structure.

2. (Canceled)

3. (Previously Presented) The curable composition of claim 1, wherein the compound having two or more epoxy groups in a molecule is a liquid at ambient temperatures.

4. (Previously Presented) The curable composition of claim 1, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.

5. (Previously Presented) The curable composition of claim 1, wherein the solid particles have a volume average particle size of 0.05 – 50 µm.

6-7. (Canceled)

8. (Previously Presented) The curable composition of claim 3, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.

9-10. (Canceled)

11. (Previously Presented) The curable composition of claim 3, wherein the solid particles have a volume average particle size of 0.05 - 50 µm.

12. (Canceled)

13. (Previously Presented) The curable composition of claim 4, wherein the solid particles have a volume average particle size of 0.05 - 50  $\mu\text{m}$ .

14. (Canceled)

15. (Previously Presented) The curable composition of claim 8, wherein the solid particles have a volume average particle size of 0.05 - 50  $\mu\text{m}$ .

16. (Canceled)